Surface Mount Schottky Power Rectifier

SMA Power Surface Mount Package

Employing the Schottky Barrier principle in a large area metal-to-silicon power diode. State of the art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity diodes in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bent Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Very Low Forward Voltage Drop
- Guardring for Stress Protection
- NRVBA Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 70 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Cathode Lead Indicated by Polarity Band
- ESD Ratings:
 - ◆ Machine Model = C
 - ♦ Human Body Model = 3B
- Device Meets MSL 1 Requirements



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SCHOTTKY BARRIER RECTIFIER 3.0 AMPERES 40 VOLTS



SMA CASE 403D STYLE 1



MARKING DIAGRAM



A34 = Device Code

A = Assembly Location**

Y = Year WW = Work Week • = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRA340T3G	SMA (Pb-Free)	5,000 / Tape & Reel
NRVBA340T3G	SMA (Pb-Free)	5,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

^{**}The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	40	V
Average Rectified Forward Current (At Rated V _R , T _L = 100°C)	I _O	3.0	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	100	Α
Storage/Operating Case Temperature	T _{stg} , T _C	-55 to +150	°C
Operating Junction Temperature (Note 1)	TJ	-55 to +150	°C
Voltage Rate of Change (Rated V _R , T _J = 25°C)	dv/dt	10,000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance – Junction–to–Lead (Note 2) Thermal Resistance – Junction–to–Ambient (Note 2)	$R_{ hetaJL} \ R_{ hetaJA}$	15 81	°C/W

^{2.} Mounted on 2" Square PC Board with 1" Square Total Pad Size, PC Board FR4.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Val	Unit	
Maximum Instantaneous Forward Voltage (Note 3)	V _F	T _J = 25°C	T _J = 100°C	Volts
(I _F = 3.0 A)		0.450	0.390	
Maximum Instantaneous Reverse Current	I _R	T _J = 25°C	T _J = 100°C	mA
(V _R = 40 V)		0.3	15	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

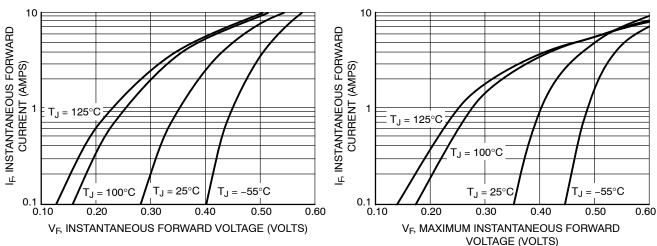


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

^{1.} The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

^{3.} Pulse Test: Pulse Width ≤ 250 μs, Duty Cycle ≤ 2.0%.

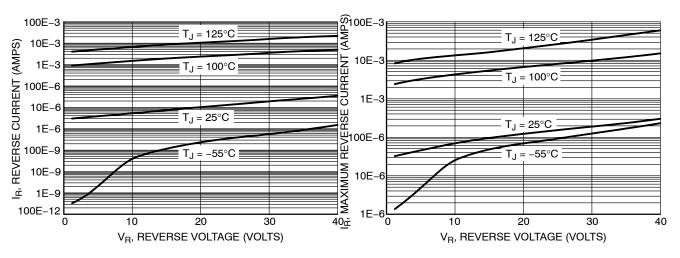


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

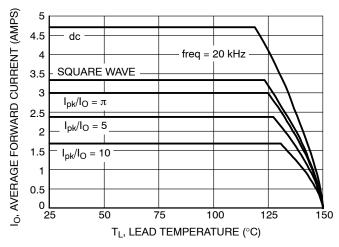


Figure 5. Current Derating

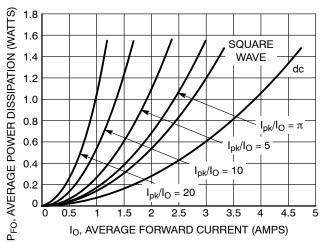


Figure 6. Forward Power Dissipation

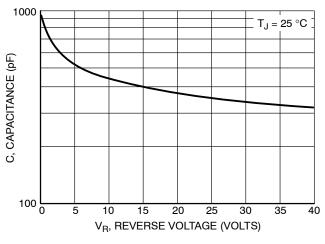


Figure 7. Capacitance

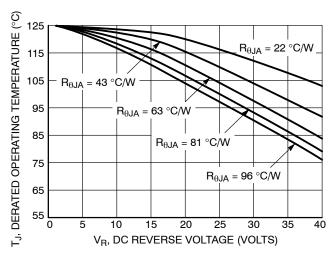


Figure 8. Typical Operating Temperature
Derating

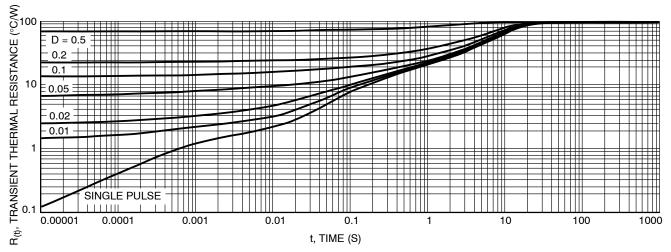


Figure 9. Thermal Response, Junction-to-Ambient (min pad)

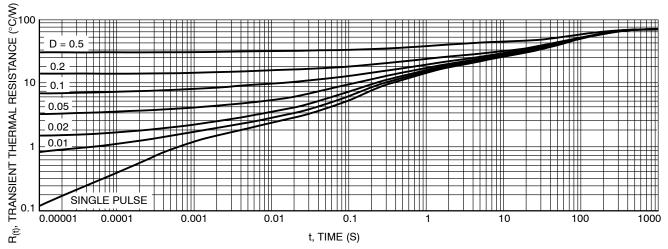
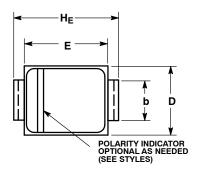


Figure 10. Thermal Response, Junction to Ambient (1 inch pad)

PACKAGE DIMENSIONS

SMA CASE 403D ISSUE H



NOTES:

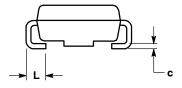
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L.

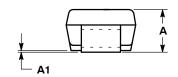
	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.97	2.10	2.20	0.078	0.083	0.087	
A1	0.05	0.10	0.20	0.002	0.004	0.008	
b	1.27	1.45	1.63	0.050	0.057	0.064	
С	0.15	0.28	0.41	0.006	0.011	0.016	
D	2.29	2.60	2.92	0.090	0.103	0.115	
E	4.06	4.32	4.57	0.160	0.170	0.180	
HE	4.83	5.21	5.59	0.190	0.205	0.220	
L	0.76	1.14	1.52	0.030	0.045	0.060	

STYLE 1:

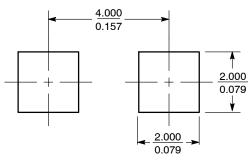
PIN 1. CATHODE (POLARITY BAND)

2 ANODE





SOLDERING FOOTPRINT*



SCALE 8:1 $\left(\frac{mm}{inches}\right)$

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.